



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-09-18
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance* true Legal declaration* Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H7S7Z8J6	2348*485XXXY	A	9991	2024-09-18
Amount	Unit of measure	Unit type	ST ECOPACK grade	
104	mg	Each	ECOPACK® 2	

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
3	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Tin - 3.5Ag	Not Applicable	NAC	0
Comment	Package : A02Y UFBGA 10X10 144L P 0.8 MM 8526251		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
,	

QueryList : REACH-27th June 2024	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	2348*485XXX		104.0004		6000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or Dies	Other Organic Materials	2.625	mg	supplier	Silicon	Silicon	7440-21-3		2.519	mg	959714	24223.46626				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.013	mg	4780	120.648619				
				supplier	metallization	Copper (Cu)	7440-50-8		0.039	mg	14937	377.0143142				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.000	mg	85	2.145425233				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.006	mg	2475	62.46973472				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	427	10.77760676				
				supplier	metallization	Tungsten (W)	7440-33-7		0.000	mg	85	2.145425233				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.046	mg	17497	441.6294741				
				supplier	Substrate	Copper	7440-50-8		2.650	mg	73000	25479.7191				
				supplier	Substrate	Continuous Filament Fiber Glass	65997-17-3		6.897	mg	190000	66317.07711				
Substrate (A30151)	Copper & its alloys	36.300	mg	supplier	Substrate	Bismaleimide	105391-33-1		2.592	mg	71400	24921.2595				
				supplier	Substrate	Triazine	25722-66-1		2.541	mg	70000	24432.60736				
				supplier	Substrate	Epoxy Resin	Proprietary		0.617	mg	17000	5933.633215				
				supplier	Substrate	Inorganic filler	Proprietary		0.690	mg	19000	6631.707711				
				supplier	Substrate	Copper (Cu)	7440-50-8		6.534	mg	190000	62826.70463				
				supplier	Substrate	Nickel (Ni)	7440-02-0		1.249	mg	34400	12006.88133				
				supplier	Substrate	Gold (Au)	7440-57-5		0.189	mg	5200	1814.993689				
				supplier	Substrate	Acrylate resin	Proprietary		1.815	mg	50000	17451.8624				
				supplier	Substrate	Barium sulfate	7727-43-7		2.904	mg	80000	27922.97984				
				supplier	Substrate	3-methoxy-3-methyl butylacetate	103429-90-9		2.541	mg	70000	24432.60736				
				supplier	Substrate	Dipropylene glycol monomethyl ether	34590-94-8		2.541	mg	70000	24432.60736				
				supplier	Substrate	Epoxy resin	Proprietary		0.363	mg	10000	3490.37248				
				supplier	Substrate	Epoxy resin (MW ≤ 7 0 0 , Carc. cat. 3 ; R40 ,	Proprietary		1.089	mg	30000	10471.11744				
				supplier	Substrate	Talc containing no asbestos fibers	14807-96-6		1.089	mg	30000	10471.11744				
				DAF (ATB-125-12)	Precious metals	3.772	mg	supplier	Glue or tape	Butadiene, acrylonitrile polymer, carboxy-termin	68610-41-3		2.452	mg	650000	23574.91803
								supplier	Glue or tape	Formaldehyde, polymer with (chloromethyl)oxir	37382-79-9		0.943	mg	250000	9067.276166
supplier	Glue or tape	Dapsone	80-08-0						0.226	mg	60000	2176.14628				
supplier	Glue or tape	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8						0.075	mg	20000	725.3820933				
supplier	Glue or tape	Reaction product: bisphenol-A-(epichlorhydrin);	25068-38-6						0.075	mg	20000	725.3820933				
Bonding wire (Cu)	Precious metals	0.915	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		0.883	mg	965500	8494.157227				
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.028	mg	31000	272.7279897				
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.003	mg	3500	30.7918698				
Encapsulation (KE-G1250AAS)	Other inorganic materials	53.549	mg	#N/A	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		48.194	mg	900000	463406.658				
				supplier	Molding Compound	Epoxy resin	Proprietary		2.838	mg	53000	27289.50319				
				supplier	Molding Compound	Phenol resin	Proprietary		2.303	mg	43000	22140.54033				
				supplier	Molding Compound	Carbon Black	1333-86-4		0.214	mg	4000	2059.585147				
Solder Ball(96.5Sn 3.5Ag)	Other Nonferrous metals & alloys	6.839	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		6.600	mg	965000	63457.80821				
				supplier	Matte Sn	Silver (Ag)	7440-22-4		0.239	mg	35000	2301.578536				